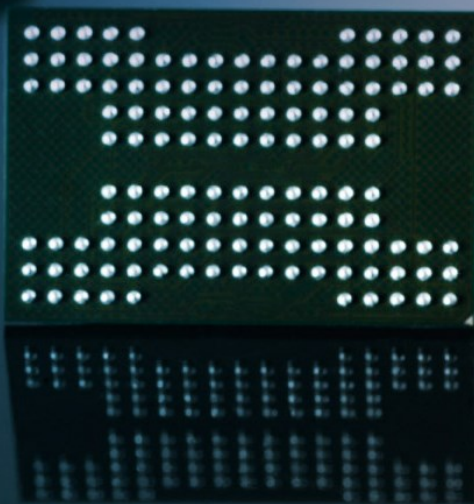


PRODUCTS



PRODUCTS eMMC PRODUCTS eMMC

Specifications

Density	Product	NAND Information	Part Number	Package Size	Package Type
4GB	eMMC4.5	1ynm 32Gb	H26M31001HPR	11.5x13x0.8	153ball FBGA
8GB	eMMC5.1	1ynm 64Gb	H26M41208HPR	11.5x13x0.8	153ball FBGA
16GB	eMMC5.1	1ynm 64Gb	H26M52208FPR	11.5x13x0.8	153ball FBGA
	eMMC5.1	1znm 128Gb	H26M51002KPR	11.5x13x0.8	153ball FBGA
32GB	eMMC5.1	1ynm 64Gb	H26M64208EMR	11.5x13x1.0	153ball FBGA
	eMMC5.1	1znm 128Gb	H26M62002JPR	11.5x13x0.8	153ball FBGA
64GB	eMMC5.1	1ynm 64Gb	H26M78208CMR	11.5x13x1.0	153ball FBGA
	eMMC5.1	1znm 128Gb	H26M74002HMR	11.5x13x1.0	153ball FBGA
128GB	eMMC5.1	3D-V2 128Gb	H26M88002AMR	11.5x13x1.0	153ball FBGA
	eMMC5.1	3D-V4 256Gb	H26T87001CMR	11.5x13x1.0	153ball FBGA

Firmware Features

JEDEC Version	Features	SK hynix Version			
		v4.41	v4.5	v5.0	v5.1
	HS200	X	0	0	0
	Discard	X	0	0	0
	Power Off Notification	X	0	0	0
	Packed Command	X	0	0	0

JEDEC Version	Features	SK hynix Version			
		v4.41	v4.5	v5.0	v5.1
eMMC4.5	Cache	X	0	0	0
	Data Tag	X	0	0	0
	Sanitize	X	0	0	0
	Context ID	X	0	0	0
	Large Sector Size	X	0	0	0
	Real Time Clock	X	0	0	0
	Dynamic Device Capacity	X	0	0	0
	Extended Partition Types	X	0	0	0
	Auto-BKOP	X	0	0	0
eMMC5.0	HS400	X	X	0	0
	Field FW update	X	X	0	0
	PON-Sleep Clarification	X	X	0	0
	Health(Smart) Report	0	0	0	0
	Production State Awareness	X	X	0	0
eMMC5.1	CMD Queuing (Optional)	X	X	X	0
	Cache Barrier	X	X	X	0
	Cache Flushing Report	X	X	X	0
	RPMB throughput Improve	X	X	0	0
	BKOP control	X	X	X	0
	HCI for CMD queuing	X	X	X	0
	Enhanced Strobe	X	X	X	0
	Secure Write Protection (Optional)	X	X	X	0

Automotive Product List

Part Number	Density	Organization	Temperature	Product Grade*	Voltage	PKG	Product Status
H26M41103HPRA	8GB	SDP	-40°C ~ 85°C	AT	3.3V/1.8V	FBGA	Mass Production
H26M41103HPRI	8GB	SDP	-40°C ~ 85°C	IT	3.3V/1.8V	FBGA	Mass Production
H26M52103FMRA	16GB	DDP	-40°C ~ 85°C	AT	3.3V/1.8V	FBGA	Mass Production
H26M52103FMRI	16GB	DDP	-40°C ~ 85°C	IT	3.3V/1.8V	FBGA	Mass Production
H26M64103EMRA	32GB	QDP	-40°C ~ 85°C	AT	3.3V/1.8V	FBGA	Mass Production
H26M64103EMRI	32GB	QDP	-40°C ~ 85°C	IT	3.3V/1.8V	FBGA	Mass Production
H26M78103CCRA	64GB	ODP	-40°C ~ 85°C	AT	3.3V/1.8V	FBGA	Mass Production
H26M78103CCRI	64GB	ODP	-40°C ~ 85°C	IT	3.3V/1.8V	FBGA	Mass Production

* 1) AT part is in compliance with AEC-Q100 and also developed based on the Automotive base-line.

2) IT part is in compliance with TS16949 and provides the same device longevity as AT parts.

Technical Support



Green Product policy



CO₂ Calculator



Global Network



Distributor



RMA/Warranty



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